

6. (Twice Amended) A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is a liquid crystal device including a pair of substrates opposing each other and a liquid crystal sealed between the substrates.

8. (Amended) A liquid crystal device comprising:  
a substrate having first and second sides;  
a liquid crystal panel opposed to the first side of the substrate;  
a plurality of external-connecting terminals formed on the liquid crystal panel;  
a plurality of substrate-side terminals formed on the first side of the substrate and opposed to the external-connecting terminals;  
an adhesive material disposed between the substrate and the liquid crystal panel;  
a plurality of wirings formed on the second side of the substrate; and  
a compensation member formed on the second side of the substrate.

9. (Amended) The liquid crystal device of Claim 8, the compensation member having substantially the same thickness as the wirings.

Please add the following new claims.

13. (New) A connection assembly comprising:  
a substrate having first and second sides;  
a target object opposed to the first side of the substrate;;  
a plurality of target object-side terminals formed on the target object;

a plurality of substrate side terminals formed on the first side of the substrate, and opposed to the target object-side terminals;

an adhesive material disposed between the substrate and the target object;

a plurality of wirings formed on the second side of said substrate; and

a compensation member formed on the second side of the substrate, the compensation member having substantially the same thickness as the wirings.

14. (New) A connection assembly comprising:

a substrate having first and second sides;

an IC chip opposed to the first side of the substrate;

a plurality of bumps formed on the IC chip;

a plurality of lands formed on the first side of the substrate, and opposed to the bumps;

an adhesive material disposed between the substrate and the IC chip;

a plurality of wirings formed on the second side of the substrate; and

a compensation member formed on the second side of the substrate, the compensation member having substantially the same thickness as the wirings.